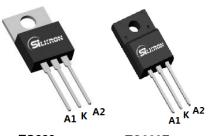
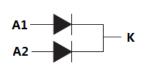


Main Product Characteristics:

IF	60A
VRRM	200V
T _j (max)	175 ℃
Vf(max)	0.95V





TO220 TO220F SSMD60200CT SSMD60200CTF

Schematic Diagram

Features and Benefits:

- High Junction Temperature
- High ESD Protection
- High Forward & Reverse Surge capability



Description:

Schottky Barrier Rectifier designed for high frequency switch model power supplies such as adaptors and DC/DC convertors; this product special design for high forward and reverse surge capability

Absolute Rating:

Symbol	Characterizes	Value	Unit
V_{RRM}	Peak Repetitive Reverse Voltage	200	V
$V_{R(RMS)}$	RMS Reverse Voltage	140	V
I _{F(AV)}	Average Forward Current	60	Α
I _{FSM}	Non Repetitive Surge Forward Current(tp=8.3ms sinusoidal)	300	Α
I _{RRM}	Peak Repetitive Reverse Surge Current(Tp=2us)	0.5	А
T_J	Maximum operation Junction Temperature Range	-55~175	$^{\circ}\!\mathbb{C}$
T_{stg}	Storage Temperature Range	-55~175	$^{\circ}\!\mathbb{C}$

Thermal Resistance

Symbol	Characterizes	Value	Unit	
$R_{ heta JC}$	Maximum Thermal Resistance Junction To	2	℃W	
$R_{\theta JC}$	Case(per leg)	TO220F	4	°C/W

Electrical Characterizes @T_A=25℃ unless otherwise specified

Symbol	Characterizes		Тур	Max	Unit	Test Condition
V_R	Reverse Breakdown Voltage				٧	I _R =0.5mA
\/ Forward \/altaga Drop				0.95	\/	I _F =30A, T _J =25℃
V _F Forward Voltag	Forward Voltage Drop			0.9	V	I _F =30A, T _J =125℃
I _R	Leakage Current			0.1	mΛ	V _R =200V, T _J =25℃
				5	mA	V _R =200V, T _J =125℃

Version: 1.0



I-V Curves:

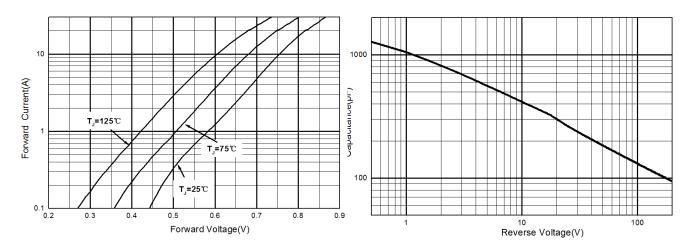


Figure 1: Typical Forward Characteristics Figure 2: Typical Capacitance Characteristics

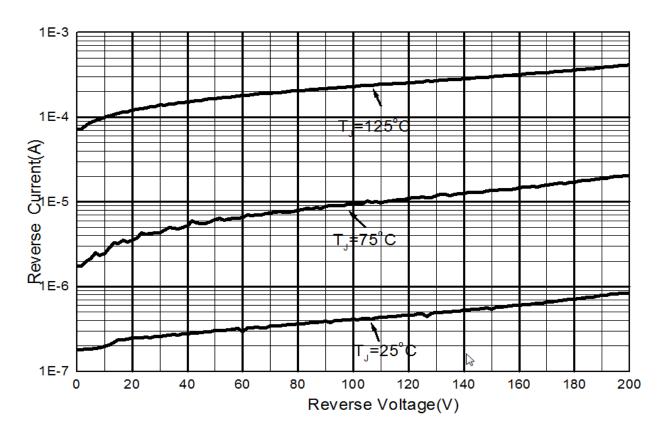
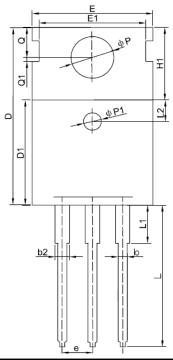
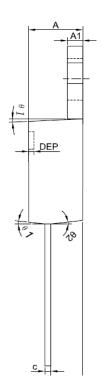


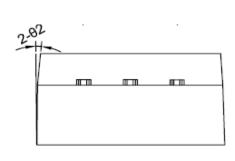
Figure 3: Typical Reverse Characteristics



Mechanical Data: TO220:



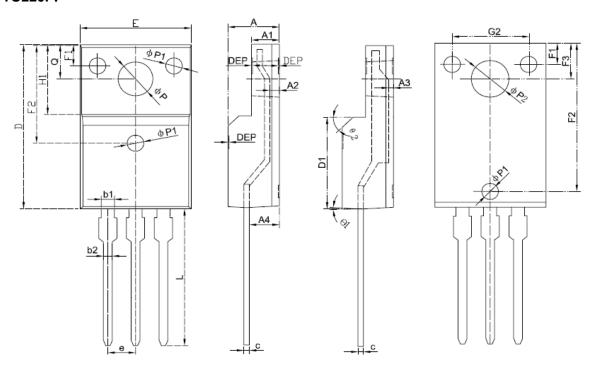




Cumbal	Dime	Dimension In Millimeters			Dimension In Inches			
Symbol	Min	Nom	Max	Min	Nom	Max		
Α	4.400	4.550	4.700	0.173	0.179	0.185		
A1	1.270	1.300	1.330	0.050	0.051	0.052		
A2	2.590	2.690	2.790	0.102	0.106	0.110		
b	0.770	-	0.900	0.030	-	0.035		
b2	1.230	-	1.360	0.048	-	0.054		
С	0.480	0.500	0.520	0.019	0.020	0.020		
D	15.100	15.400	15.700	-	0.606	-		
D1	9.000	9.100	9.200	0.354	0.358	0.362		
DEP	0.050	0.285	0.520	0.002	0.011	0.020		
Е	10.060	10.160	10.260	0.396	0.400	0.404		
E1	-	8.700	-	-	0.343	-		
ФР1	1.400	1.500	1.600	0.055	0.059	0.063		
е		2.54BSC 0.1BSC						
e1		5.08BSC			0.2BSC			
H1	6.100	6.300	6.500	0.240	0.248	0.256		
L	12.750	12.960	13.170	0.502	0.510	0.519		
L1	-	-	3.950	-	-	0.156		
L2		1.85REF			0.073REF			
ФР	3.570	3.600	3.630	0.141	0.142	0.143		
Q	2.730	2.800	2.870	0.107	0.110	0.113		
Q1	-	0.200	-	-	0.008	-		
0 1	5°	7 ⁰	9º	5°	7°	9º		
Θ2	1 ⁰	3 ⁰	5°	10	3 ⁰	5 ⁰		



TO220F:



Comphal	Dimension In Millimeters			Dimension In Inches		
Symbol	Min	Nom	Max	Min	Nom	Max
E	9.960	10.160	10.360	0.392	0.400	0.408
Α	4.500	4.700	4.900	0.177	0.185	0.193
A1	2.340	2.540	2.740	0.092	0.100	0.108
A2	0.950	1.050	1.150	0.037	0.041	0.045
A3	0.420	0.520	0.620	0.017	0.020	0.024
A4	2.650	2.750	2.850	0.104	0.108	0.112
С	-	0.500	-	-	0.020	-
D	15.670	15.870	16.070	0.617	0.625	0.633
Q	3.200	3.300	3.400	0.126	0.130	0.134
H1	6.480	6.680	6.880	0.255	0.263	0.271
е		2.54BSC		0.10BSC		
ФР	-	3.183	-	-	0.125	-
L	12.780	12.980	13.180	0.503	0.511	0.519
D1	8.990	9.190	9.390	0.354	0.362	0.370
ФР1	1.400	1.500	1.600	0.055	0.059	0.063
ФР2	-	3.450	-	-	0.136	-
0 1	4°	5°	6°	4°	5°	6°
Θ2	-	45°	-	-	45°	-
DEP	0.050	0.100	0.150	0.002	0.004	0.006
F1	1.900	2.000	2.100	0.075	0.079	0.083
F2	8.980	9.180	9.380	0.354	0.361	0.369
F3	3.200	3.300	3.400	0.126	0.130	0.134
G2	6.900	7.000	7.100	0.272	0.276	0.280
b1	1.170	1.205	1.240	0.046	0.047	0.049
b2	0.770	0.810	0.850	0.030	0.032	0.033



Ordering and Marking Information

Device Marking: SSMD60200CT&SSMD60200CTF

Package (Available)
TO-220&TO220F
Operating Temperature Range
C:-55 to 175 °C

Devices per Unit

Package Type	Units/ Tube	Tubes/Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/ Carton Box
TO220	50	20	1000	6	6000
TO220F	50	20	1000	6	6000

Reliability Test Program

Test Item	Conditions	Duration	Sample Size
High	Tj=125℃ to 175℃ @	168 hours	3 lots x 77 devices
Temperature	80% of Max	500 hours	
Reverse	VDSS/VCES/VR	1000 hours	
Bias(HTRB)			

Version: 1.0



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